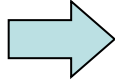


Characteristics

- High purity
- High Density
- High thermal conductivity



Features

- Fewer metal contamination on wafers
- Excellent outgas performance and few particles
- Excellent cooling rate and thermal response

Products

Applications	Products
Plasma Etch system / apparatus	Shower plate, Focus ring etc.
Plasma CVD apparatus , thermal CVD apparatus	Susceptor etc.
Thermal processing apparatus	Susceptor, wafer holder etc.



Fig.1 Focus ring



Fig.2 Shower plate